

## SMT Test Point Series



Components Corporation announces the 100% RoHS-compliant TP-108 series of ultra-low profile test points. The surface mount devices feature a 0.060 inches profile, and a 0.070 inches  $\times$  0.135 inches pad size. The TP-108 is constructed utilizing a proprietary technology which includes the utilization of flat wire to facilitate a larger area for mounting the device to the board. This bigger area is a significant benefit as it helps minimize mechanical stress on the devices' connections to the solder pad to enhance the durability and reliability of the connection for miniature probes, clips and j-hooks. Moreover, the test points' loop configuration holds these devices securely, and eliminates the potential for slippage and puncture wounds frequently associated with posts and turrets.

Components Corporation

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<http://www.wirelessdesignmag.com/product-releases/2005/10/smt-test-point-series?qt-blogs=0>